

IN THE SPECIFICATION

No new matter is added to the application by virtue of the specification amendments presented herein. The amendments presented herein are merely to correct obvious typographical errors.

Page 3, lines 12-23 - Please replace this paragraph with the following amended paragraph:

Sacrificial assembly 200 comprises sacrificial layer 210 and release coating 220. Sacrificial layer 210 is preferably formed from a relatively cheap material such as a polyester or a celluloid film. Release coating 220 preferably is located between the sacrificial layer 210 and base layer assembly 100, and comprises standard silicon, Teflon[®] or graphite release agents such as commercially available materials which are available from Chemlease[™] and Buehler[™]. An example of such a commercially available material is POL-ESE 233[™]. In other embodiments, the sacrificial layer assembly 200 may not include release coating 220, particularly if using materials with low natural surface energy and low adhesion to other materials, such as Teflon[®] and oriented polyimide. In a less-preferred embodiment, the sacrificial layer is not removed but becomes part of the final structure. It is contemplated that in many embodiments, traces of the release coating 220 will remain after removal of sacrificial layer ~~[[100]]~~ 200.

Page 4, lines 15-18 – Please replace this paragraph with the following amended paragraph:

If conductive vias are used, it is contemplated that such vias will comprise a solder paste rather than a transient liquid phase sintered material. Preferred solder pastes include PbSn, PbSnAg, ~~Indium~~ indium alloys, and ~~[[Au]]~~ gold eutectic/alloys, if wire piercing/thermosonic ball formation is used.~~[[.]]~~

Page 4, lines 22-30 and page 5, lines 1-5: Please replace this paragraph with the following amended paragraph:

A preferred method of forming pre-form assembly 10 comprises: providing sacrificial layer 210, coating sacrificial ~~layer~~ layer 210 with release coating 220, applying a thermosetting material 100 on top of release coating 220; curing the thermosetting material 100 to form a B-stage layer; inserting through conductors 300 into thermosetting material 100. Insertion of through conductors 300 preferably comprises either piercing wires 300 into the thermosetting material, or lasing or drilling and subsequently filling holes in thermosetting material 100. The lased vias may be processed by "off-set" lasing to provide a larger bottom diameter footprint, to lessen registration to contact point difficulty. A preferred method of using pre-form assembly 10 comprises: providing an IC; providing a supporting surface to which the IC is to be mechanically and electrically bonded; providing pre-form assembly 10; applying pre-form assembly 10 to either the IC or supporting surface; peeling away sacrificial layer 210; sandwiching pre-form assembly 10 between the IC and the supporting surface; and curing the base layer assembly of pre-form assembly 10.